



Material Content Data Sheet



Sales Product Name	BGB 719N7ESD E6327			Issued		29. August 2013		
MA#	MA000949840							
Package	PG-TSNP-7-6			Weight*		2.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.049	2.29	2.29	22926	22926
leadframe	non noble metal	zinc	7440-66-6	0.002	0.09		887	
	non noble metal	tin	7440-31-5	0.002	0.11		1109	
	non noble metal	chromium	7440-47-3	0.003	0.13		1331	
	non noble metal	copper	7440-50-8	0.939	44.02	44.35	440167	443494
wire	noble metal	gold	7440-57-5	0.032	1.48	1.48	14762	14762
encapsulation	organic material	carbon black	1333-86-4	0.005	0.23		2311	
	plastics	epoxy resin	-	0.143	6.70		67027	
	inorganic material	silicondioxide	60676-86-0	0.839	39.29	46.22	392919	462257
leadfinish	non noble metal	tin	7440-31-5	0.066	3.11	3.11	31079	31079
plating	noble metal	silver	7440-22-4	0.020	0.92	0.92	9213	9213
glue	plastics	epoxy resin	-	0.007	0.33		3254	
	noble metal	silver	7440-22-4	0.028	1.30	1.63	13015	16269
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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